Hyperspectral Cathodoluminescence Imaging Of Low Resistivity Large Bandgap AlGaN Layers

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Motivation

There are many interesting applications for semiconductor devices emitting in the UV spectral region, which include: water purification, gas sensing and medical diagnostics. To realize these multi-quantum well based UV-light emitting devices, high quality AlGaN layers are required, for which challenges remain in their growth. One of the main limitations for the application of AlGaN layers with a high AlN content (x>80%) in devices is the inefficient doping. There are only a few reports of Si doping of large bandgap AlGaN layers and most of the studied samples were highly resistive. Due to this the influence of the Si doping on the luminescence properties and the morphology of high AlN content AlGaN layers are barely understood.

A series of samples with different SiH₄/group-III ratios (1.9, 5.9 and 18-10⁻⁵) in the top $AI_{0.82}Ga_{0.18}N$ layer was grown by metalorganic vapour phase epitaxy (MOVPE) on

MOVPE growth

- Close coupled showerhead reactor
- Substrate:
- Epitaxial lateral overgrown (ELO) AIN/Al₂O₃
- Precursors: TMGa, TMAI, NH₃, SiH₄

Cathodoluminescence hyperspectral imaging

- All measurements at room temperature
- 5 kV acceleration Voltage

sity

 ~ 100 nm penetration depth according to Monte Carlo simulations



defect reduced AIN buffers. Using cathodoluminescence (CL) hyperspectral imaging we have investigated the influence of the Si doping on the luminescence properties and morphology of the samples.

Performed in a FEI Quanta 250 ESEM

1.9.10-5 SiH_//III

10 µm

Pretilted Reflecting sample holder objective Measurement Setup and mode of operation for Hyperspectral CL

Morphology and luminescence properties of Al_{0.82}Ga_{0.18}N:Si



1.9·10⁻⁵ → 5.8·10⁻⁵ SiH₄/III, decreasing resisitivity → three peaks AlGaN NBE (5.36 eV), Two DAP peaks: $(V_{III}-2O_N)^-$ and $(V_{III}-O_N)^{2-}$ (4.35 eV, 3.39 eV) [2] 5.8·10⁻⁵ → 1.8·10⁻⁴ SiH₄/III increasing resistivity, additional Peak: V_{III}^{3-} (2.95 eV) [2,3]

 \rightarrow Self compensation, caused by formation of V_{III}³⁻

5.8.10⁻⁵ SiH₄/III

2. Morphology



- 1.9-10⁻⁵ SiH₄/III, surface governed by hillocks, high V-pit density

Hillocks

- 5.8-10⁻⁵ SiH₄/III, increasing hillock height and surface roughness, reduced V-pit density
- 1.8-10⁻⁴ SiH₄/III, step bunches with a periodicity of 3.5 μ m, hillocks on terraces
 - -----> Change in surface morphology due to different substrate miscut

3. CL hyperspectral imaging



1.9.10⁻⁵ SiH₄/III

NBE intensity 1000 3000 2000 1000

NBE Emission energy

Step bunches

1.8.10⁻⁴ SiH₄/III

component in apex of hillocks(white arrows) → hillocks form due to spiral growth different terrace width of hillocks → different GaN incorporation → cause of the observed variation in NBE intensity and emission energy

Electron Channeling Contrast Imaging (ECCI) [5] and CL performed on same area

Influence of defects and Cross-section analysis

5.8-10-5 SiH₄/III

Strong periodic reduction in emission intensity with a periodicity of 3.5 µm

Threading dislocations (TD) acting as non radiative recombination centers

Clustering and ordering of TD density due to underlying ELO pattern [4]

4. Defects



- Small increase in AIGaN NBE intensity along growth direction

Conclusion

Morphology:

- Change in morphology (spiral growth to step bunches) is due to variation of substrate miscut



1.9-10⁻⁵ SiH₄/III, small spatial variations in intensity and emission energy
 5.8-10⁻⁵ SiH₄/III, spatial variations in intensity and emission energy
 Spatial variation caused by hillocks

1.8-10⁻⁴ SiH₄/III, increasing intensity, decreasing emission energy due to higher GaN incorporation along steps

Luminescence Properties:

- Defect luminescence changes with doping, self compensation identified by V_{III}³⁻ peak
- Morphology strongly influences luminescence properties due to compositional inhomogenities

Defects:

- Dislocation clustering is caused by the template, Strong effect on luminescence properties
- Hillocks are caused by threading dislocations with screw component

Citations

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